2SD1821, 2SD1821A

Silicon NPN epitaxial planar type

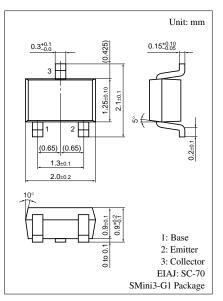
For high breakdown voltage low-frequency and low-noise amplification

Features

- \bullet High collector to emitter voltage $V_{\mbox{\scriptsize CEO}}$
- Low noise voltage NV
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing

ADSolute Maximum Hattings $T_a = 25$ C							
Parameter		Symbol	Rating	Unit			
Collector to	2SD1821	V _{CBO}	150	V			
base voltage	2SD1821A		185				
Collector to	2SD1821	V _{CEO}	150	V			
emitter voltage	2SD1821A		185				
Emitter to base voltage		V _{EBO}	5	V			
Peak collector current		I _{CP}	100	mA			
Collector current		I _C	50	mA			
Collector power dissipation		P _C	150	mW			
Junction temperature		Tj	150	°C			
Storage temperature		T _{stg}	-55 to +150	°C			

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking symbol: P (2SD1821) L (2SD1821A)

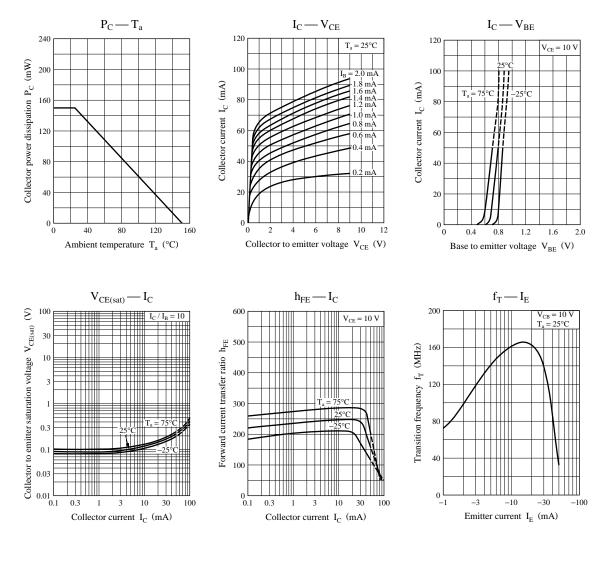
\blacksquare Electrical Characteristics $T_a = 25^{\circ}C$

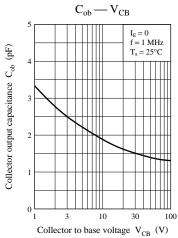
Parameter	·	Symbol	Conditions	Min	Тур	Max	Unit
Collector cutoff curren	t	I _{CBO}	$V_{CB} = 100 \text{ V}, I_E = 0$			1	μΑ
Collector to emitter	2SD1821	V _{CEO}	$I_{\rm C} = 100 \ \mu A, \ I_{\rm B} = 0$	150			V
voltage	2SD1821A			185			
Emitter to base voltage	e	V _{EBO}	$I_E = 10 \ \mu A, I_C = 0$	5			V
Forward current transfer ratio *		h _{FE}	$V_{CE} = 5 \text{ V}, I_C = 10 \text{ mA}$			330	
Collector to emitter saturation voltage		V _{CE(sat)}	$I_{\rm C} = 30 \text{ mA}, I_{\rm B} = 3 \text{ mA}$			1	V
Transition frequency		f _T	$V_{CB} = 10 \text{ V}, I_E = -10 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capac	itance	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		2.3		pF
Noise voltage		NV	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}, G_{V} = 80 \text{ dB}$		150		mV
			$R_g = 100 \text{ k}\Omega$, Function = FLAT				

Note) *: h_{FE} Rank classification

Ra	ank	R	S	
h	h _{FE1}		185 to 330	
Marking	2SD1821	PR	PS	
symbol	2SD1821A	LR	LS	

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